



<b>ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PowerPAK® SO-8</b>					
<b>STRESS</b>	<b>SAMPLE SIZE</b>	<b>DEVICE HR./CYC</b>	<b>CONDITION</b>	<b>TOTAL FAILS</b>	<b>FAIL PERCENTAGE</b>
BOND INT	1,020	490,000	200 °C + N2	0	0.00
HAST	7,282	735,100	130 °C, 85 % RH	0	0.00
Power Cycle	1,153	17,208,808	DELTA T <sub>j</sub> = 100	0	0.00
Pressure Pot	13,610	1,321,980	121°, 15 PSIG	0	0.00
Solder Dunk	2,194	9,167	260 °C, 10 s	0	0.00
Solderability	1,250	10,815	883 M2003	0	0.00
Temp. Cycle	17,943	8,139,650	- 65 °C to 150 °C	0	0.00